

# SANDIA TALKS

## HOW TO “PHOTOCOPY” A PRINTED CIRCUIT BOARD

*Eric Sorte, 5964*



# WHAT'S THE PROBLEM?



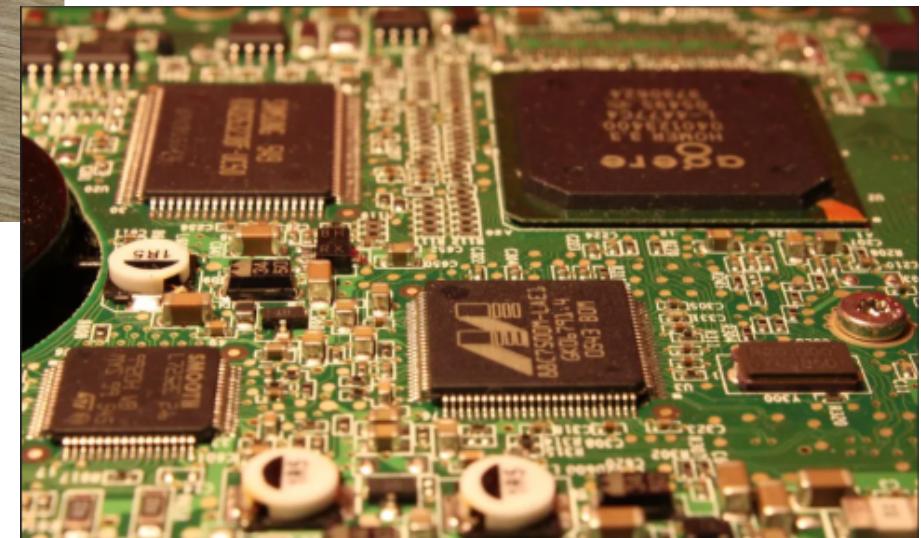
# HOW AND WHY TO COPY



2D printing



3D printing functional devices

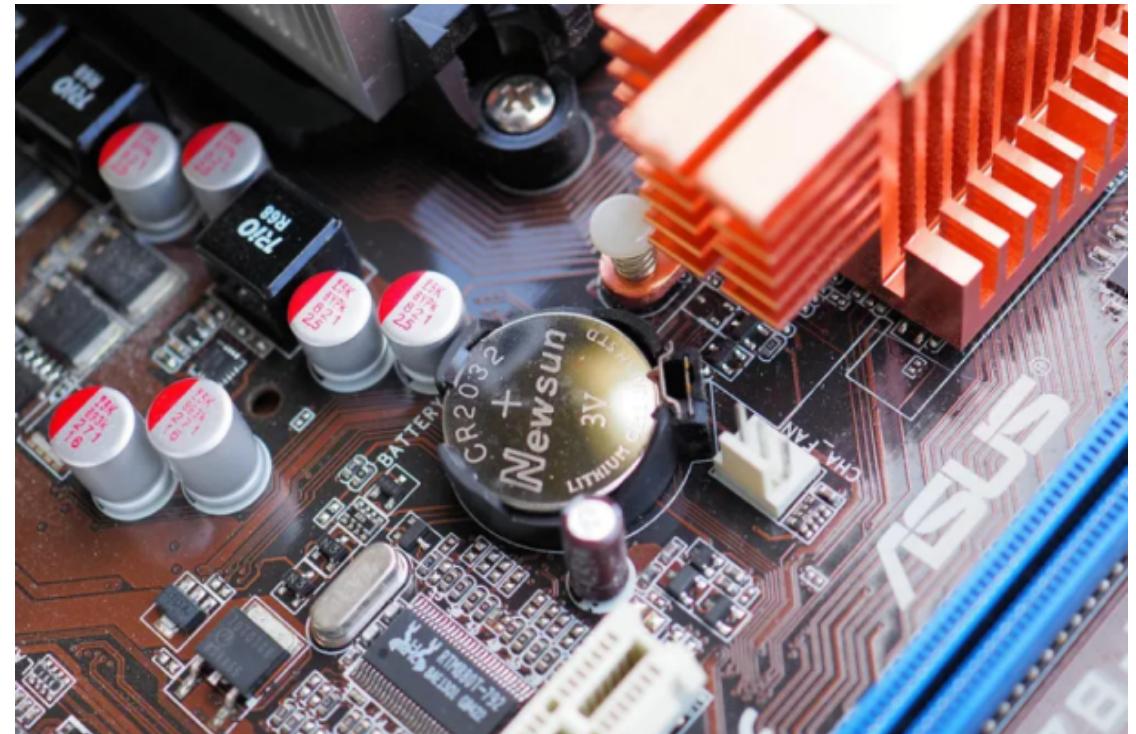


Circuit board?

# XRAY/CT



Bag of water with some bones

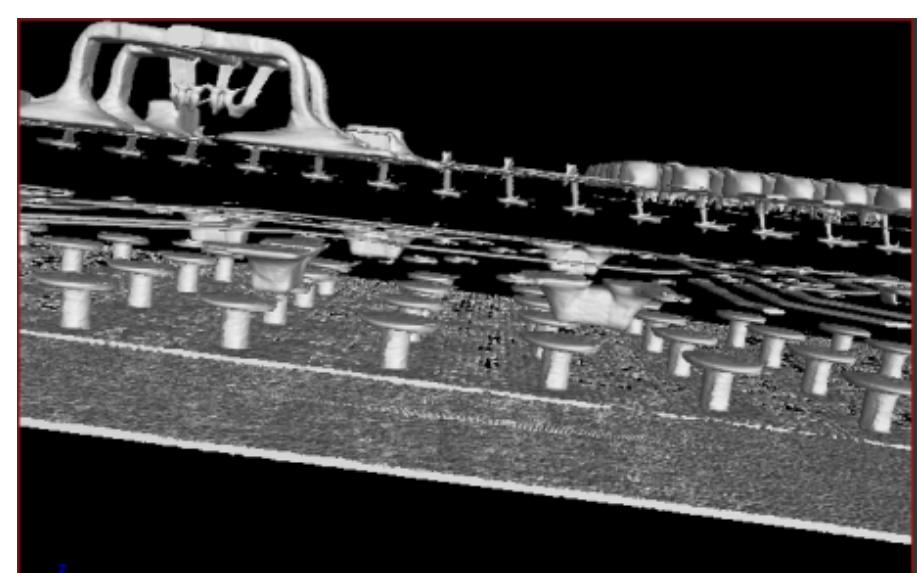
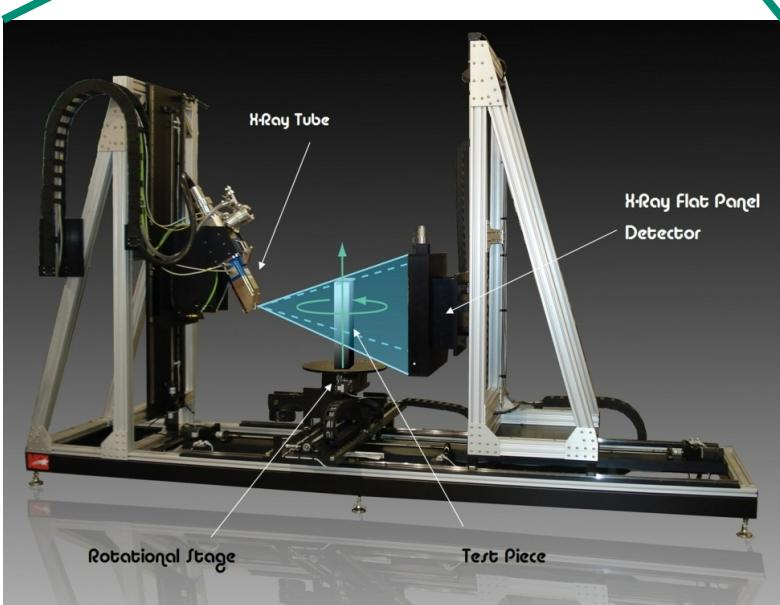


Lots of metal  
Multiple heterogeneous materials  
Multiple important layers  
Very small features (50 microns)

# INDUSTRIAL XRAY SYSTEM



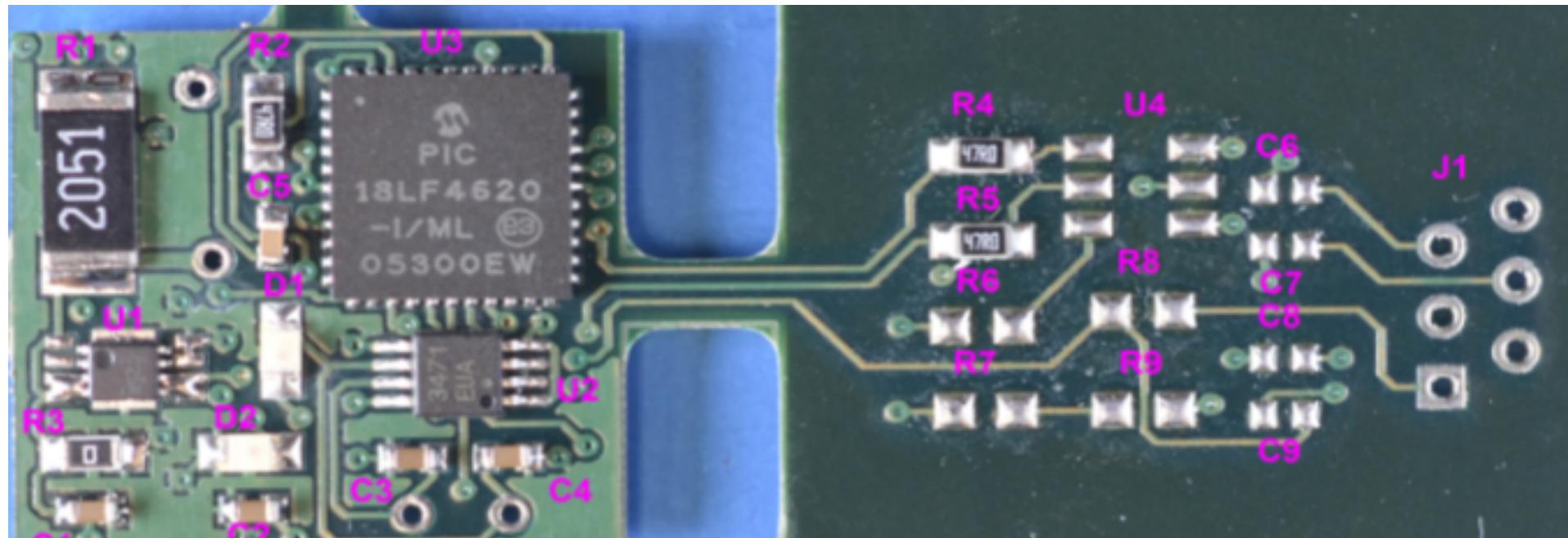
2D Xray



3D CT

# CAPABILITY PROCESS

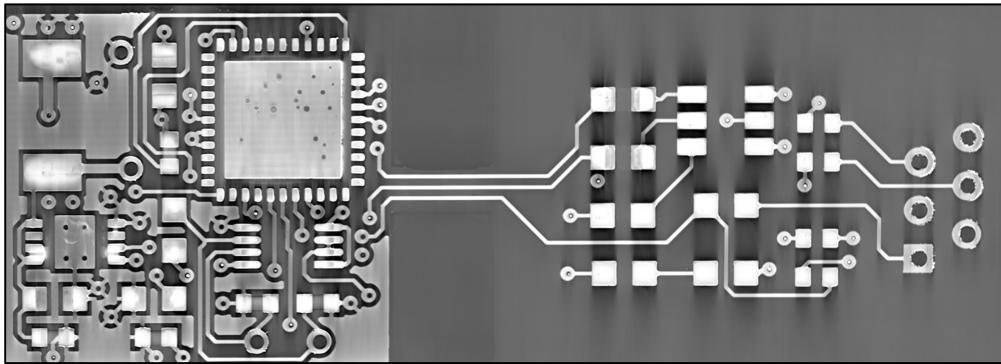
Original



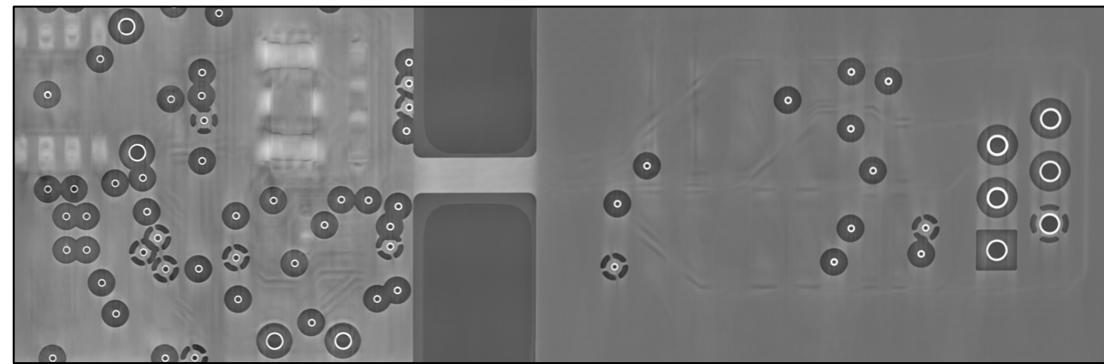
# CAPABILITY PROCESS

X-ray

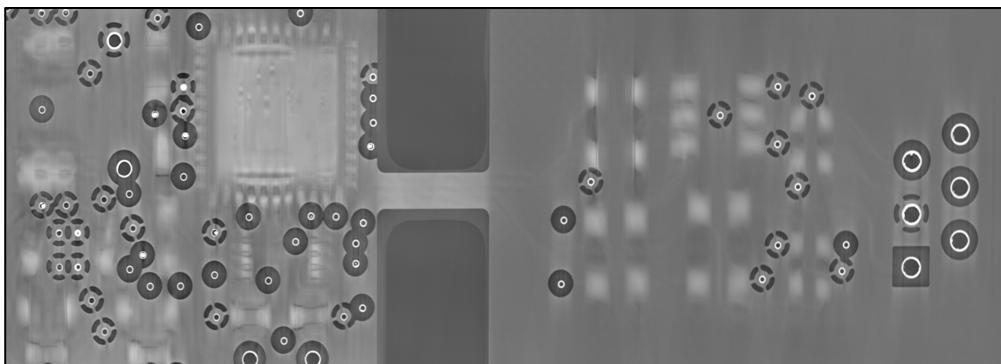
Layer 1



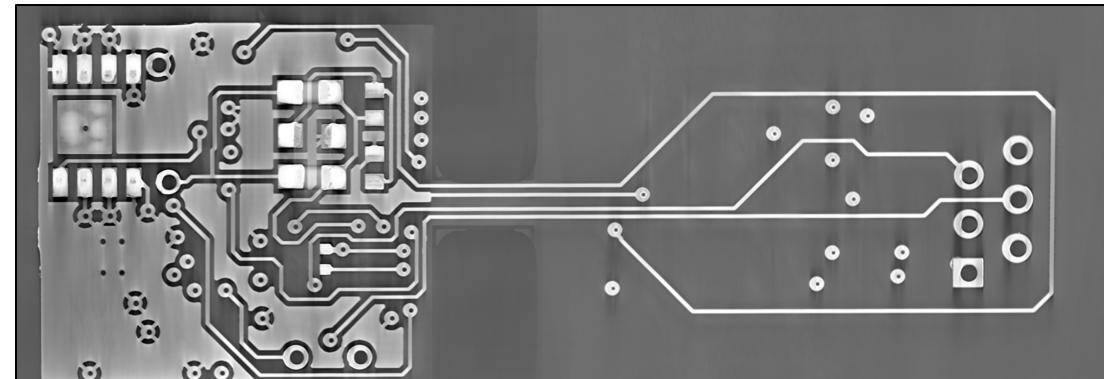
Layer 2



Layer 3

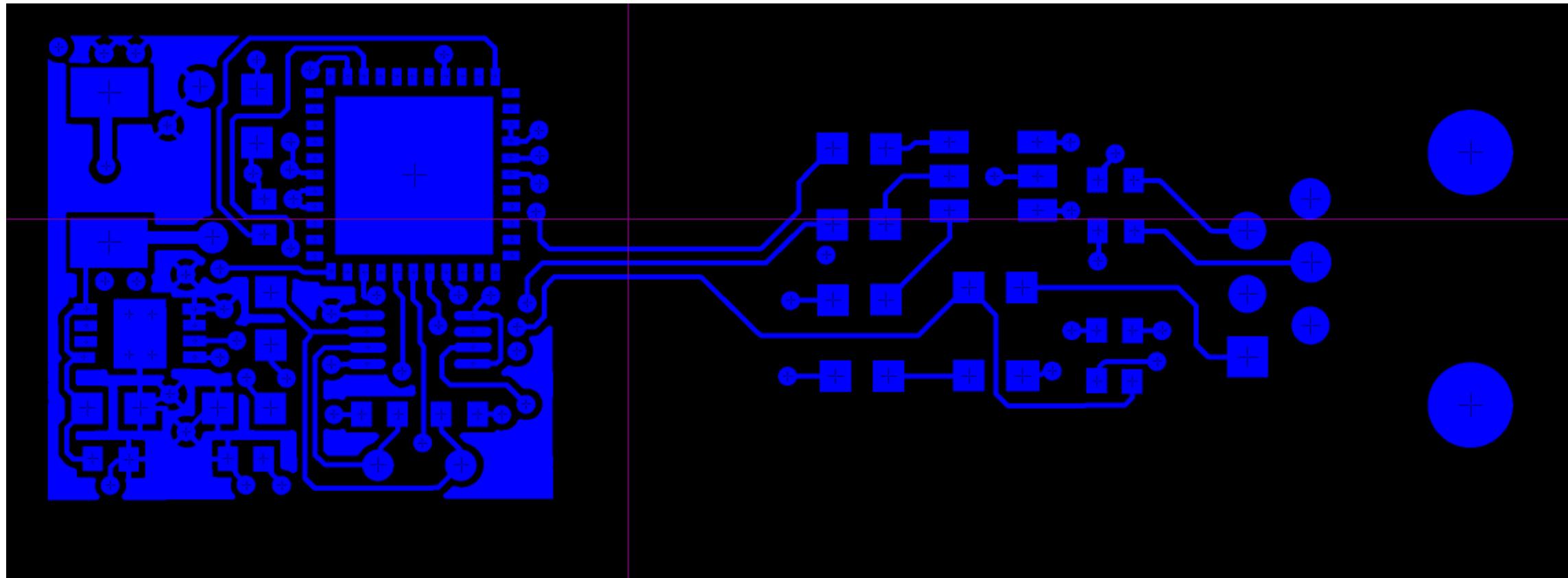


Layer 4



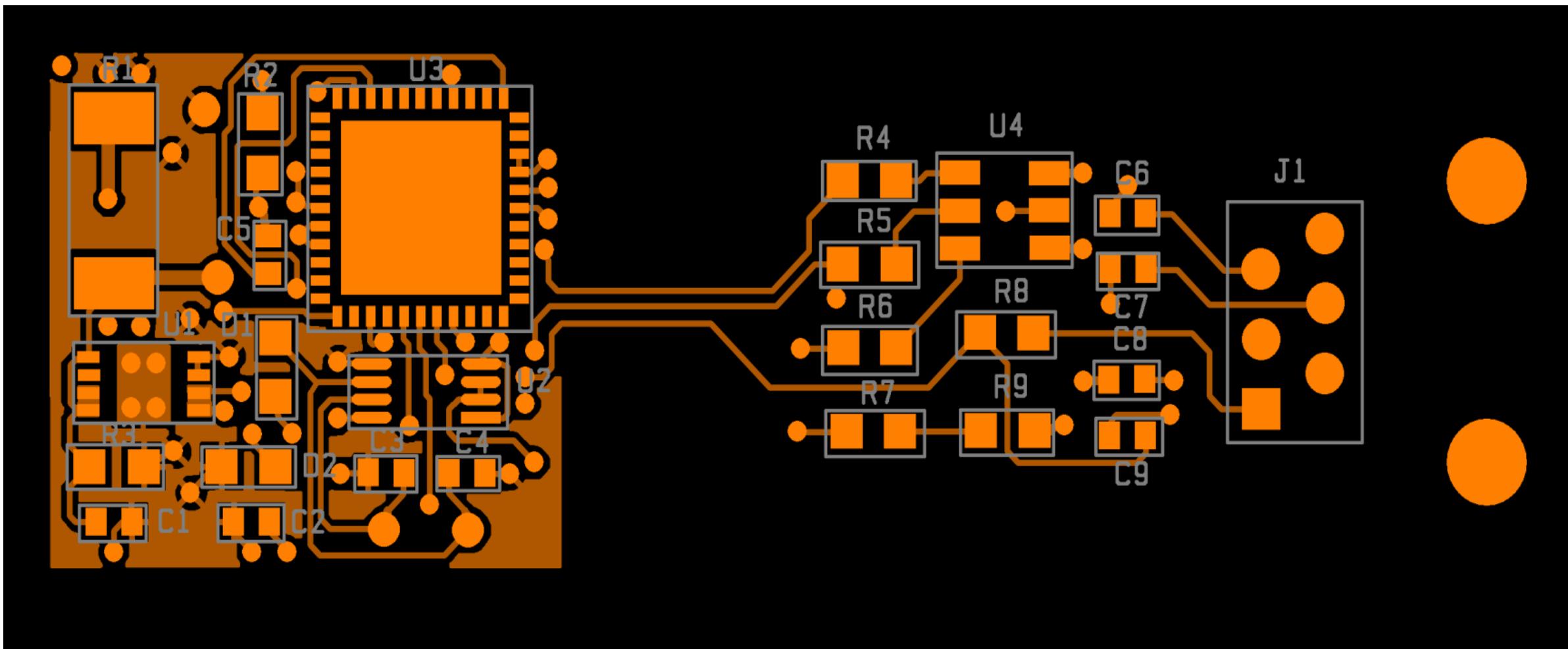
# CAPABILITY PROCESS

Binary



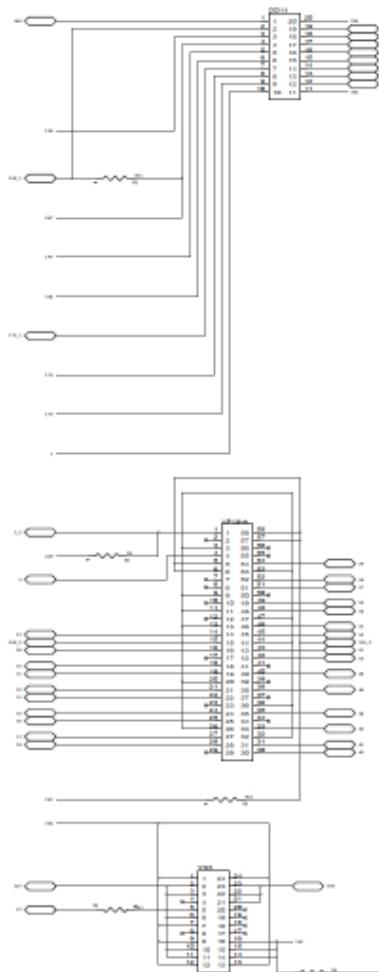
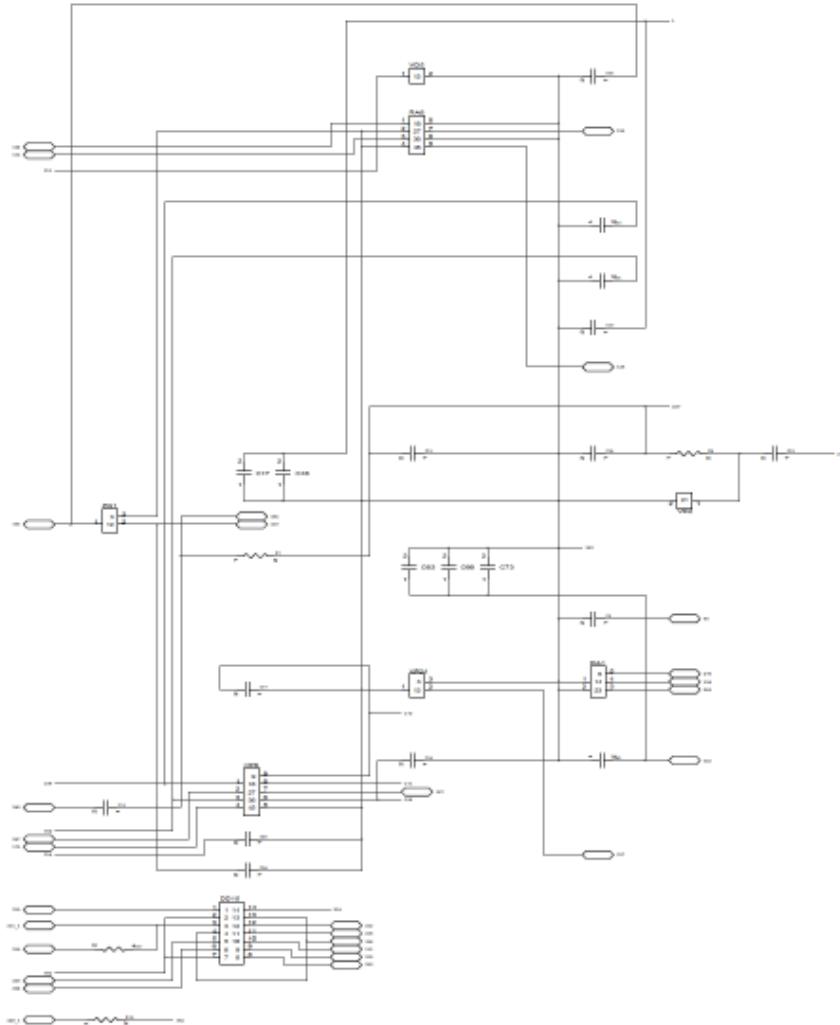
# CAPABILITY PROCESS

Design Files



# CAPABILITY PROCESS

Schematic



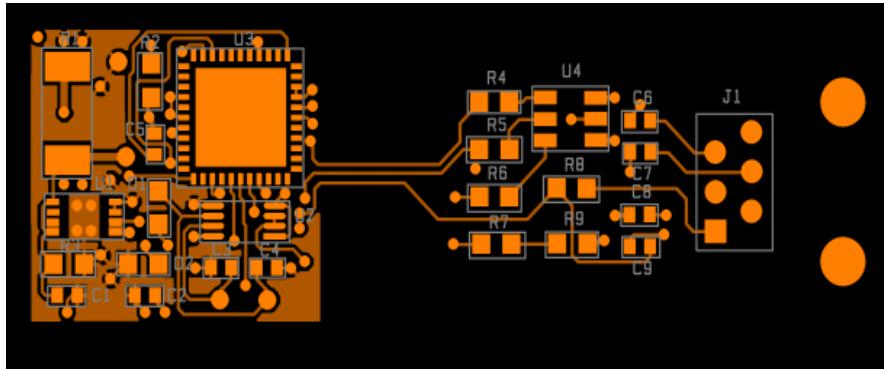
Bill of Materials



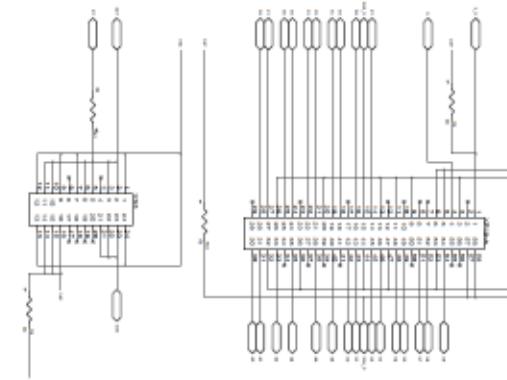
|            |          |  |            |
|------------|----------|--|------------|
| <b>1A</b>  | <b>1</b> |  | <b>VCC</b> |
| <b>1Y</b>  | <b>2</b> |  | <b>6A</b>  |
| <b>2A</b>  | <b>3</b> |  | <b>6Y</b>  |
| <b>2Y</b>  | <b>4</b> |  | <b>5A</b>  |
| <b>3A</b>  | <b>5</b> |  | <b>5Y</b>  |
| <b>3Y</b>  | <b>6</b> |  | <b>4A</b>  |
| <b>GND</b> | <b>7</b> |  | <b>4Y</b>  |

# CAPABILITY PROCESS

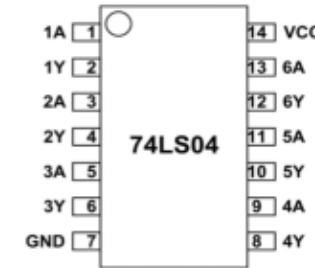
# Design Files



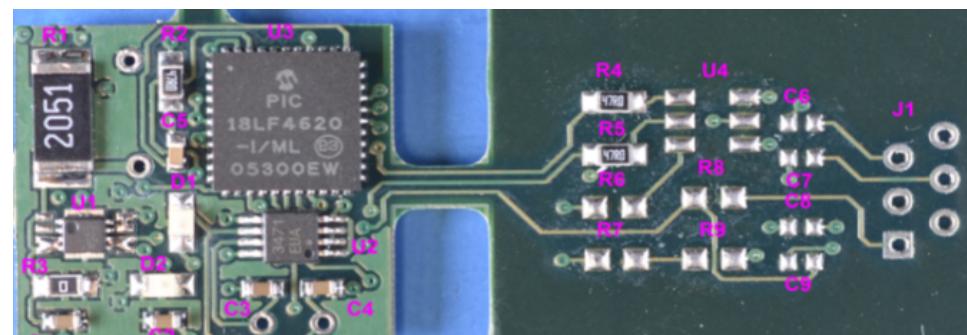
## Schematic



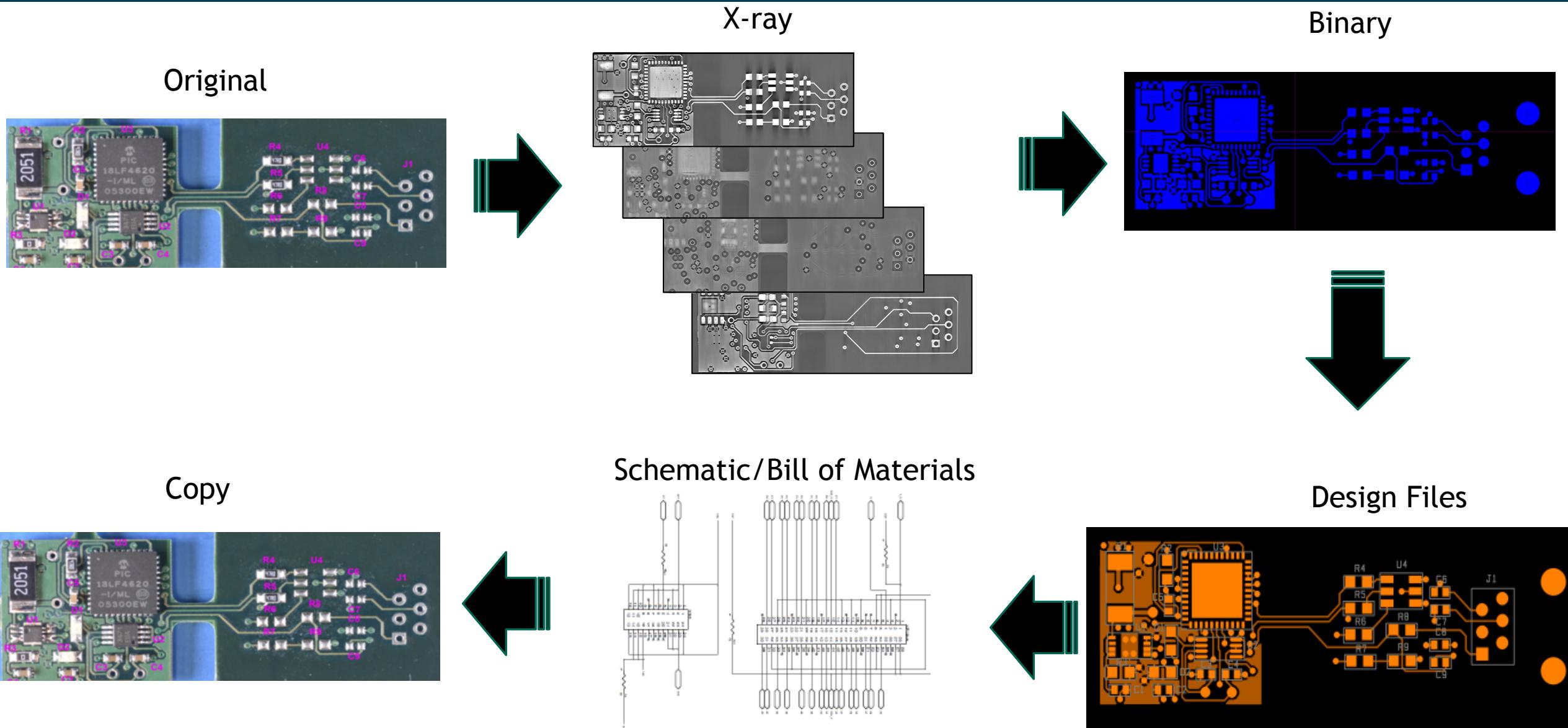
# Bill of Materials



Copy



# CAPABILITY PROCESS



# SANDIA TALKS

THANK  
YOU

